

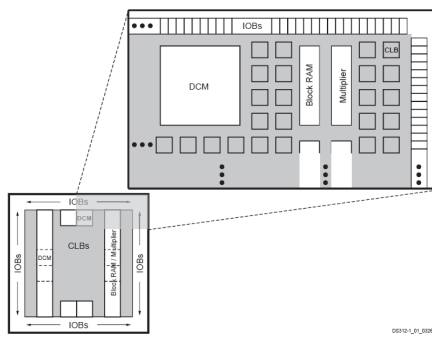
## The Spartan 3e FPGA

## The Spartan 3e FPGA

- ◆ What's inside the chip?
  - How does it implement random logic?
  - What other features can you use?
- ◆ What do all these things mean?
  - LUT, Slice, BRAM, DCM, IOB, CLB...
- ◆ Two important documents (linked to the class web site)
  - Spartan3e Family Complete Data Sheet
  - Spartan3e User Guide

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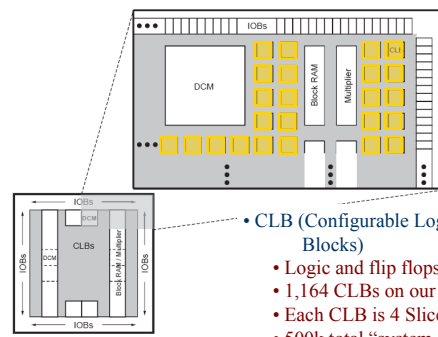
## What's on the chip?



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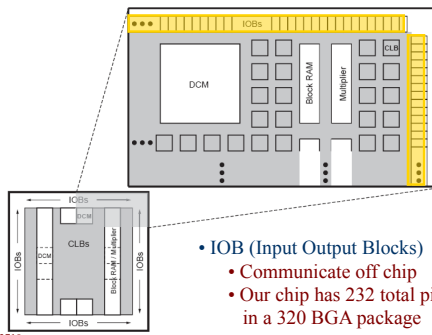
0010\_LUT\_00001

## What's on the chip?



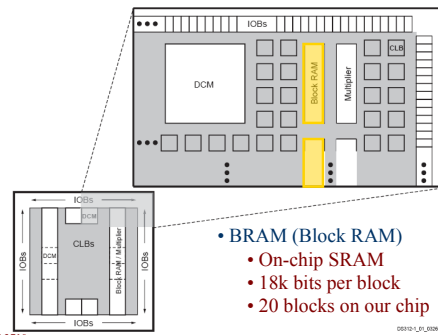
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## What's on the chip?



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## What's on the chip?



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0010\_LUT\_00001

## What's on the chip?

• Multiplier

- Custom 18x18 multiplier
- One per RAM block...

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## What's on the chip?

• DCM (Digital Clock Manager)

- Clock generation and distribution
- Four on our chip

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## What's on the chip?

• Programmable Interconnect

- Connect everything together
- Perhaps the most critical part of the chip!

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## CLB: Configurable Logic Block

◆ 4 "Slices" per CLB

- The slices work together to make logic, flip flops, distributed RAM, or shift registers
- Connected to other CLBs through Switch Matrix

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## Left and Right Slices

- SRL16 = 16-bit shift register
- RAM16 = 16-bit RAM (16x1 bit memor)
- LUT4 = four-bit lookup table (16x1 bit memor)
- SLICEM = slice that can be memory or logic
- SLICEL = slice that can only be logic

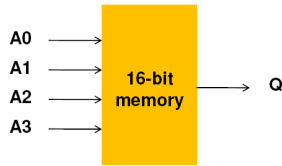
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## What's Really in a Slice?

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## LUT 4 – Basic Building Block

- RAM memory 4-bit input, 1-bit output
- Can implement any logic function of up to 4 inputs

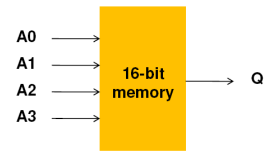
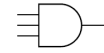


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## LUT 4 – Basic Building Block

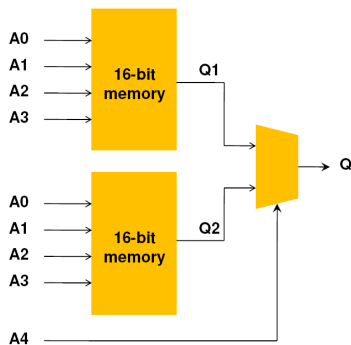
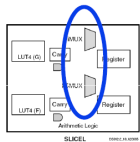
- Example: Implement 3-input AND
- Assume A0 - A2 are used

A0	A1	A2	A3	Q
0	0	0	x	0
0	0	1	x	0
0	1	0	x	0
0	1	1	x	0
1	0	0	x	0
1	0	1	x	0
1	1	0	x	0
1	1	1	x	1



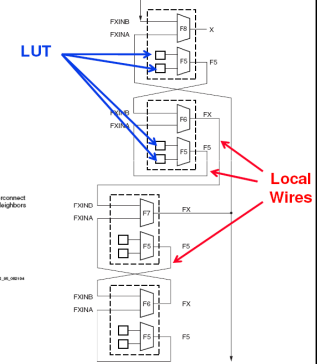
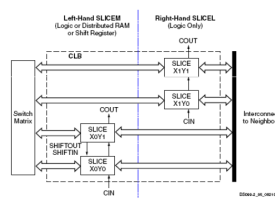
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## Slice Muxes extend LUT4



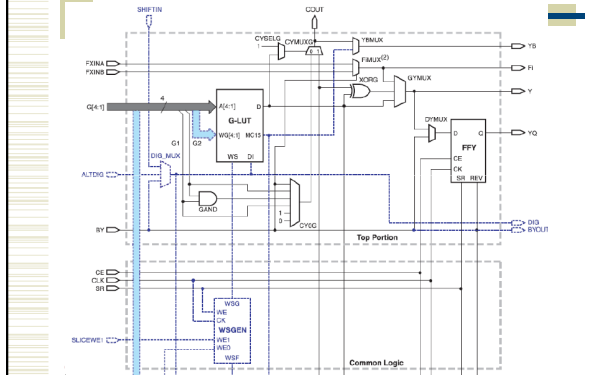
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## Once CLB – up to LUT7

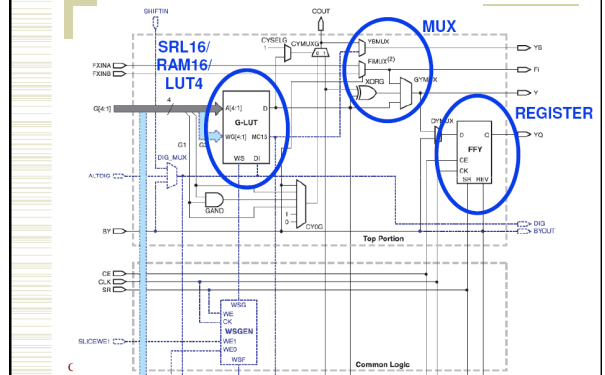


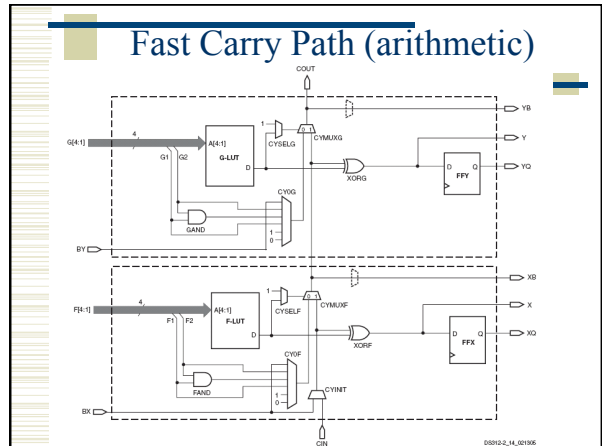
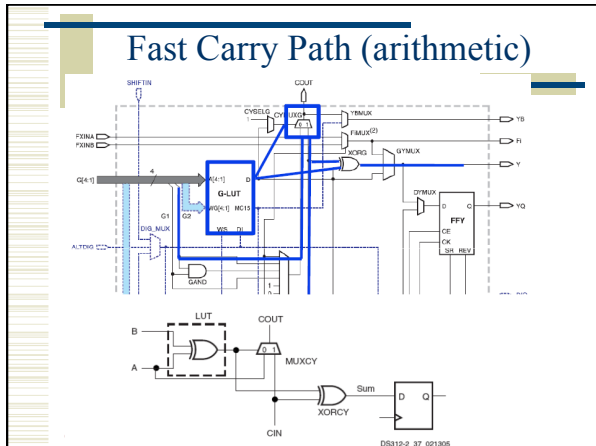
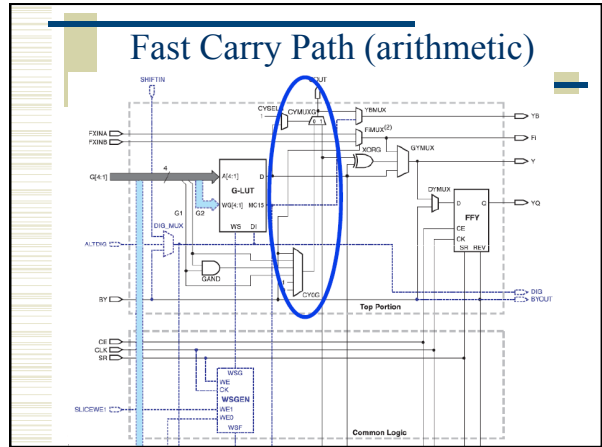
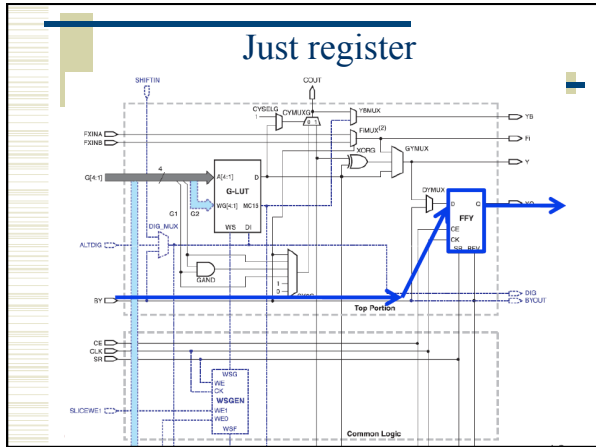
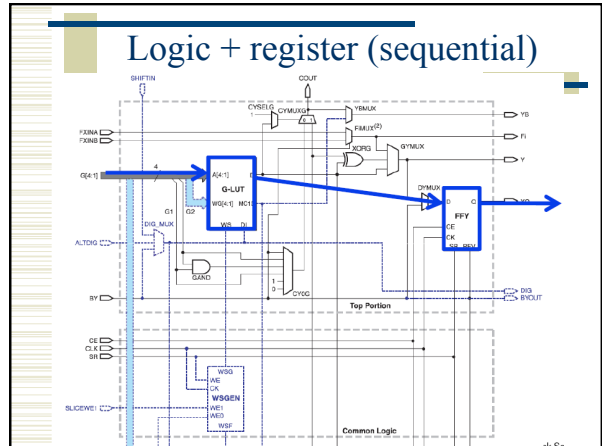
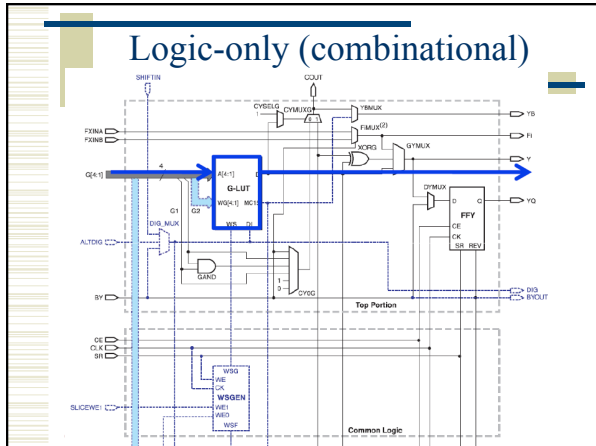
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## Top Half of a SliceM (left)



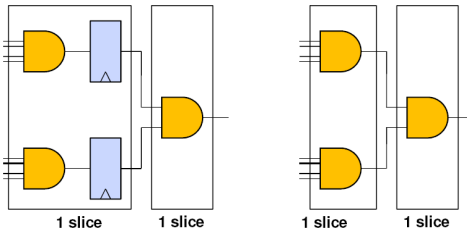
## Top Half of a SliceM (left)





## Mapping to CLBs

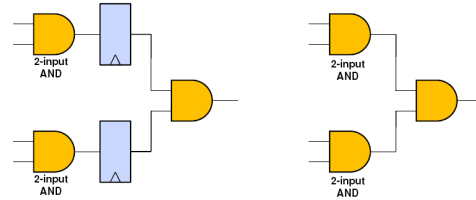
- Each LUT can go through a flip flop
  - So, these circuits map to the same number of Slices



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## Mapping to CLBs

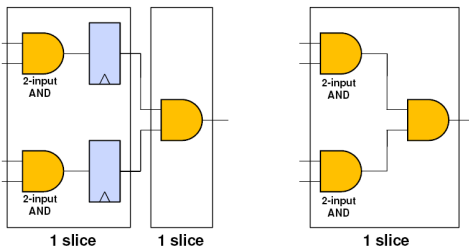
- How about these?



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## Mapping to CLBs

- How about these?



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## CLB Summary

- Each CLB = 4 slices
  - Each slice contains
    - 2 LUT-4
      - LUT can be random logic, or 16x1bit RAM or SR
    - 2 flip flop
    - MUXs
    - Carry logic
- ISE reports how many slices you use
  - among lots of other things...

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## IO Blocks

- Connections to the outside world
  - Each pin can be configured a large number of ways
  - Different signaling voltages and drive currents

Single-Ended IOSTANDARD	V <sub>CCIO</sub> Supply/Compatibility				
	1.2V	1.5V	1.8V	2.5V	3.3V
LVTTTL	-	-	-	-	Input/Output
LVCMOS33	-	-	-	-	Input/Output
LVCMOS25	-	-	-	-	Input/Output
LVCMOS18	-	-	Input/Output	Input	Input
LVCMOS15	-	Input/Output	Input	Input	Input
LVCMOS12	Input/Output	Input	Input	Input	Input
PCI93_3	-	-	-	-	Input/Output
PCI66_3	-	-	-	-	Input/Output

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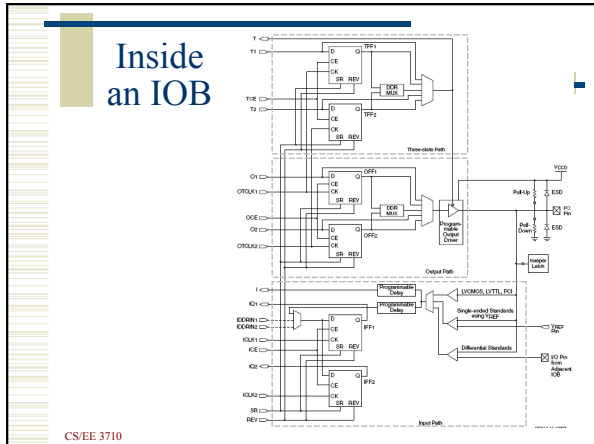
## IO Blocks

- Connections to the outside world
  - Each pin can be configured a large number of ways
  - Different signaling voltages and drive currents

NOTE! No 5v!

IOSTANDARD	Output Drive Current (mA)					
	2	4	6	8	12	16
LVTTTL	✓	✓	✓	✓	✓	✓
LVCMOS33	✓	✓	✓	✓	✓	✓
LVCMOS25	✓	✓	✓	✓	✓	✓
LVCMOS18	✓	✓	✓	✓	✓	✓
LVCMOS15	✓	✓	✓	✓	✓	✓
LVCMOS12	✓	✓	✓	✓	✓	✓

Single-Ended IOSTANDARD	V <sub>CCIO</sub> Supply/Compatibility				
	1.2V	1.5V	1.8V	2.5V	3.3V
LVTTTL	-	-	-	-	Input/Output
LVCMOS33	-	-	-	-	Input/Output
LVCMOS25	-	-	-	-	Input/Output
LVCMOS18	-	-	Input/Output	Input	Input
LVCMOS15	-	Input/Output	Input	Input	Input
LVCMOS12	Input/Output	Input	Input	Input	Input
PCI93_3	-	-	-	-	Input/Output
PCI66_3	-	-	-	-	Input/Output



## Interconnect

- ◆ Actually the most important part of the FPGA!
  - Consumes the most area on the die
  - Consumes the most power on the die
  - In most cases, wires limit the performance
- ◆ But, hardly mentioned in the datasheet
  - People are more impressed with logic

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## Interconnect

- ◆ RAM-programmable switches
  - 2,270,208 bits of configuration RAM!
  - Compare to 368,640 total bits of Block RAM
  - or 74,752 total bits of Distributed RAM (LUTs)
- ◆ Hierarchical organization
  - Many fast, short wires with small drive
  - Fewer longer wires with high drive
  - LOTS of work goes into picking just the right mix!

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## Interconnect

- CLBs connect to 'switch matrix' which connects to the on-chip network
- Each switch matrix interconnects many different wires

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## Interconnect

Four types of wires

Horizontal and Vertical Long Lines (horizontal channel shown as an example)	
Horizontal and Vertical Hex Lines (horizontal channel shown as an example)	
Horizontal and Vertical Double Lines (horizontal channel shown as an example)	
Direct Connections	

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## Clock Routing

- ◆ Routed on a separate dedicated network
  - Another reason to avoid gated clocks
- ◆ Recursive "Fish bone" network that minimizes clock skew
- ◆ Clocks come from off-chip, or from a DCM

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## Distributed RAM

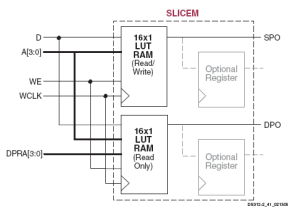
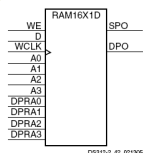


Figure 26: RAM16X1D Dual-Port Usage

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## Distributed RAM

```
parameter RAM_WIDTH = <ram_width>;
parameter RAM_ADDR_BITS = <ram_addr_bits>;

reg [RAM_WIDTH-1:0] <ram_name> [(2**RAM_ADDR_BITS)-1:0];

wire [RAM_WIDTH-1:0] <output_data>;

<reg_or_wire> [RAM_ADDR_BITS-1:0] <read_address>, <write_address>;
<reg_or_wire> [RAM_WIDTH-1:0] <input_data>;

always @(posedge <clock>)
  if (<write_enable>)
    <ram_name>[<write_address>] <= <input_data>;

assign <output_data> = <ram_name>[<read_address>];
```

Dual-Port Distributed RAM

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## Distributed RAM

```
RAM16X1D #(
  .INIT(16'h0000) // Initial contents of RAM
) RAM16X1D_inst (
  .DPO(DPO), // Read-only 1-bit data output for DPRA
  .SPO(SPO), // R/W 1-bit data output for A0-A3
  .A0(A0), // R/W address[0] input bit
  .A1(A1), // R/W address[1] input bit
  .A2(A2), // R/W address[2] input bit
  .A3(A3), // R/W address[3] input bit
  .D(D), // Write 1-bit data input
  .DPRA0(DPRA0), // Read address[0] input bit
  .DPRA1(DPRA1), // Read address[1] input bit
  .DPRA2(DPRA2), // Read address[2] input bit
  .DPRA3(DPRA3), // Read address[3] input bit
  .WCLK(WCLK), // Write clock input
  .WE(WE) // Write enable input
);
```

Dual-Port Distributed RAM

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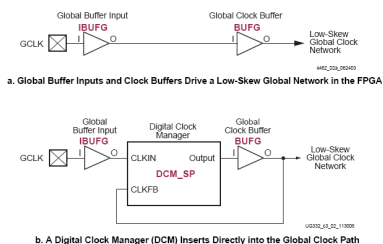
## Digital Clock Manager (DCM)

DCMs integrate advanced clocking capabilities directly into the FPGA's global clock distribution network. Consequently, DCMs solve a variety of common clocking issues, especially in high-performance, high-frequency applications:

- **Eliminate Clock Skew**, either within the device or to external components, to improve overall system performance and to eliminate clock distribution delays.
- **Phase Shift** a clock signal, either by a fixed fraction of a clock period or by incremental amounts.
- **Multiply or Divide an Incoming Clock Frequency** or synthesize a completely new frequency by a mixture of clock multiplication and division.
- **Condition a Clock**, ensuring a clean output clock with a 50% duty cycle.
- **Mirror, Forward, or Rebuffer a Clock Signal**, often to deskew and convert the incoming clock signal to a different I/O standard—for example, forwarding and converting an incoming LVTTTL clock to LVDS.
- **Any or all the above functions, simultaneously.**

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## Digital Clock Manager (DCM)



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## Digital Clock Manager (DCM)

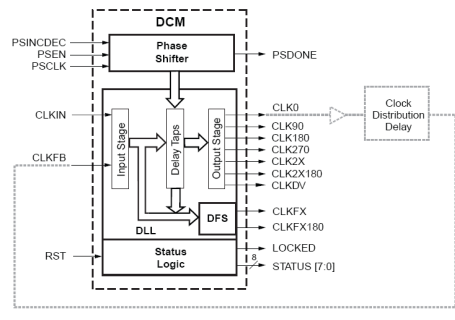
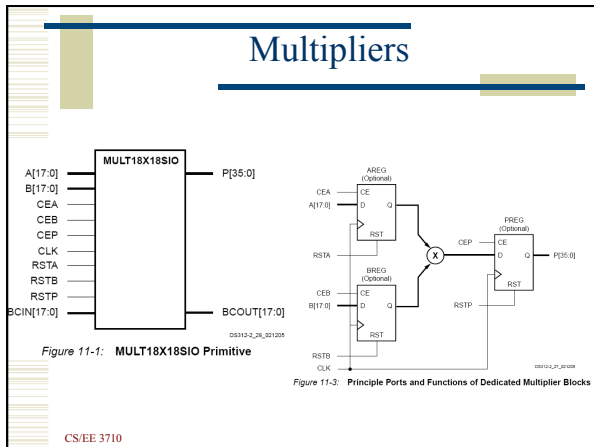
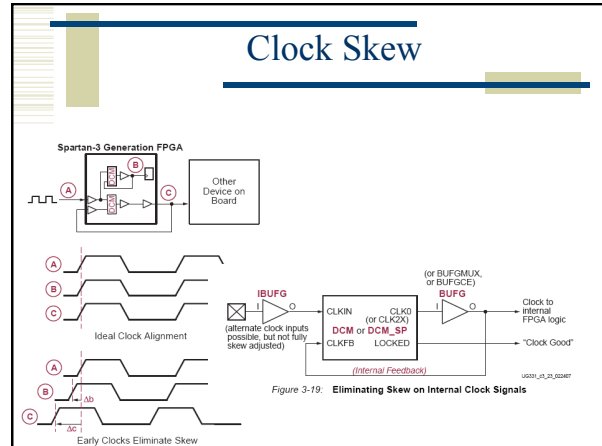
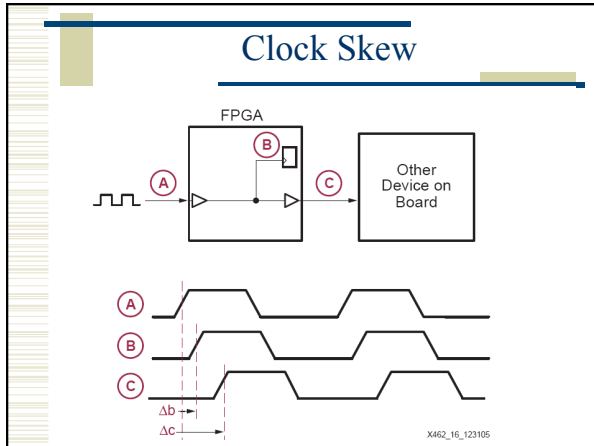


FIGURE 27-20 (continued)





## Multipliers

```

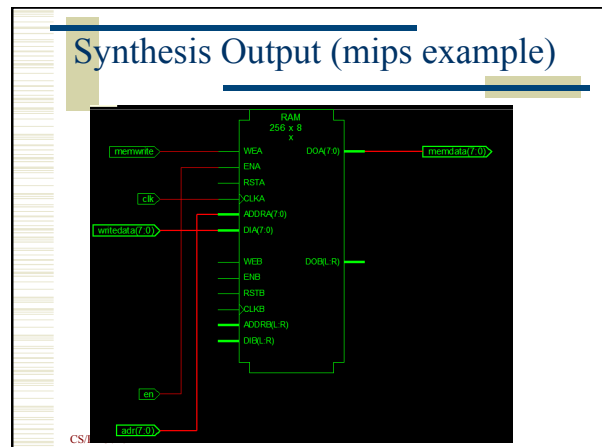
module mult18x18sio(a,b,clk,prod);
    input [7:0] a;
    input [7:0] b;
    input clk;
    output [15:0] prod;
    reg [15:0] prod;
    always @(posedge clk) prod <= a*b;
endmodule
    
```

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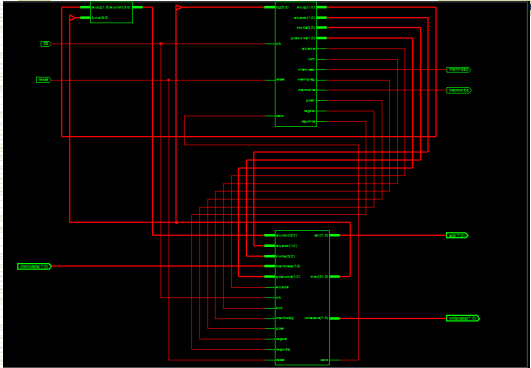
## Synthesis Output (mips example)

Device Utilization Summary			
Logic Utilization	Used	Available	Utilization
Number of Slice Flip Flops	79	9,312	1%
Number of 4 input LUTs	193	9,312	2%
<b>Logic Distribution</b>			
Number of occupied Slices	123	4,656	2%
Number of Slices containing only related logic	123	123	100%
Number of Slices containing unrelated logic	0	123	0%
<b>Total Number of 4 input LUTs</b>	<b>193</b>	<b>9,312</b>	<b>2%</b>
Number used as logic	161		
Number used for Dual Port RAMs	32		
Number of bonded <b>IDBs</b>			
Number of bonded	19	232	8%
Number of RAMB16s	1	20	5%
Number of BUFGMUXs	1	24	4%

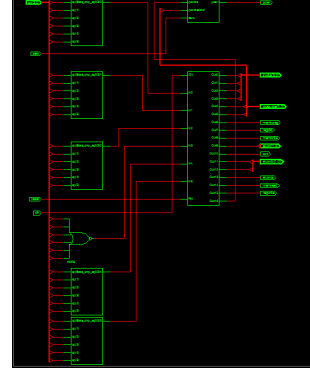
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### Synthesis Output (mips example)

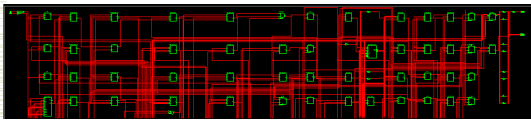


### Synthesis Output (mips example)



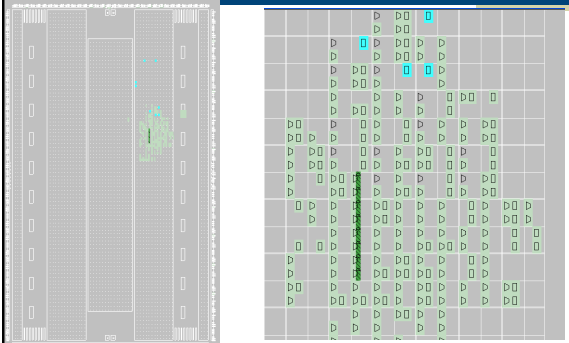
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### Synthesis Output (mips example)



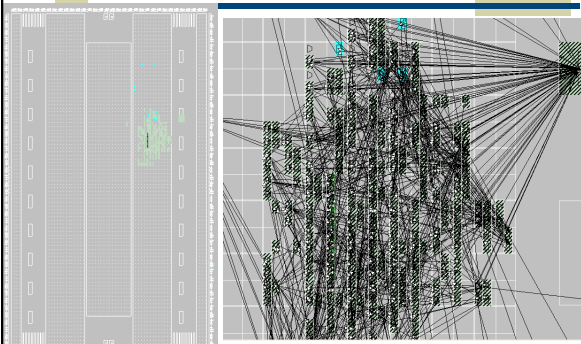
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### Implement Output (mips example)



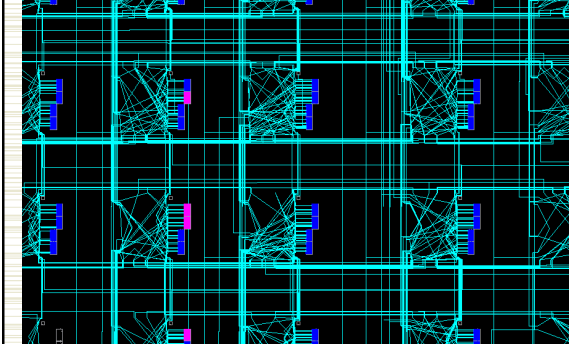
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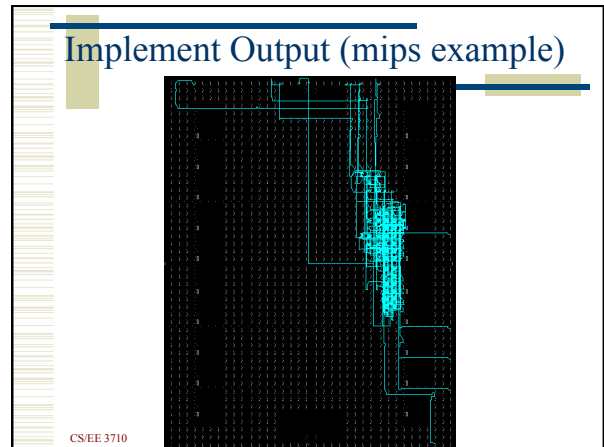
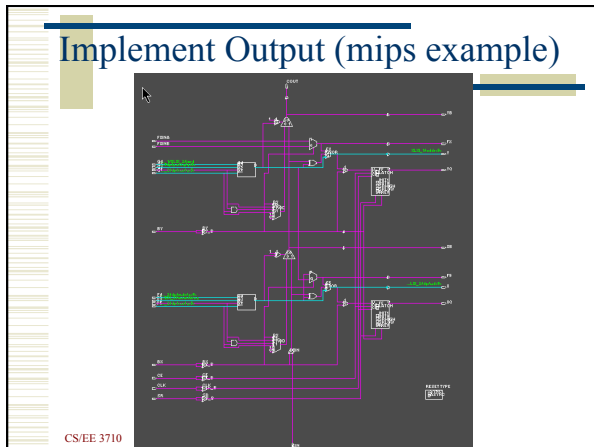
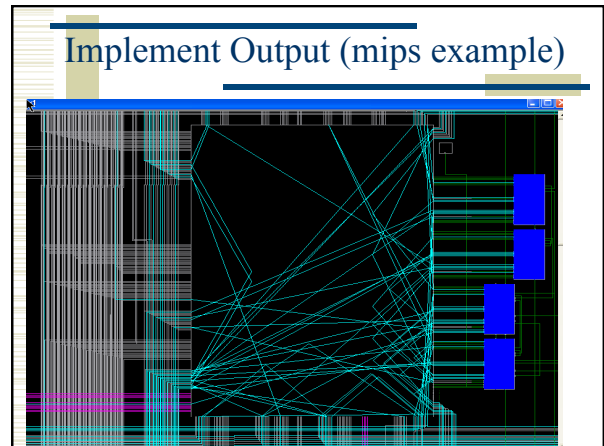
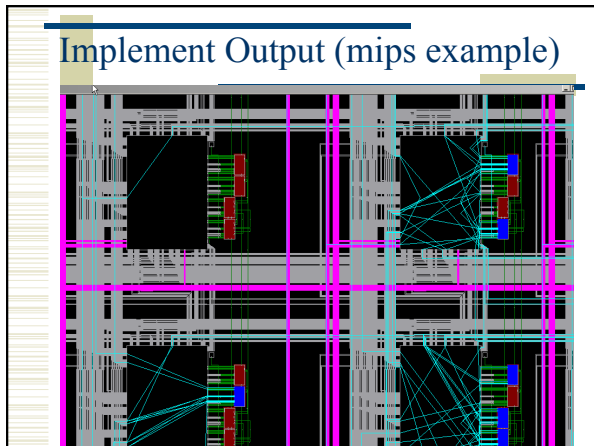
### Implement Output (mips example)



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### Implement Output (mips example)





- ### Conclusion
- ◆ **FPGAs are complex beasts!**
    - Made to be very general and flexible
  - ◆ **ASIC vs. FPGA?**
    - Rule of thumb, FPGA about 5 times slower clock than ASIC
    - FPGAs consume more power
    - FPGAs are bigger for the same function
    - ASICs are *much* more expensive to develop
      - NRE – Non-Recurring Engineering
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### ASIC vs. FPGA

FPGA & ASIC Design Advantages	ASIC Design Advantages
<b>Faster time-to-market</b> - no layout, masks or other manufacturing steps are needed	<b>Full custom capability</b> - for design since device is manufactured to design specs
<b>No upfront NRE</b> (non-recurring expenses) - costs typically associated with an ASIC design	<b>Lower unit costs</b> - for very high volume designs
<b>Simpler design cycle</b> - due to software that handles much of the routing, placement, and timing	<b>Smaller form factor</b> - since device is manufactured to design specs
<b>More predictable project cycle</b> - due to elimination of potential re-spins, wafer capacities, etc.	<b>Higher raw internal clock speeds</b>
<b>Field reprogrammability</b> - a new bitstream can be uploaded remotely	

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